

Matched N-Channel JFET Pairs

PRODUCT SUMMARY					
Part Number	$V_{GS(off)}$ (V)	$V_{(BR)GSS}$ Min (V)	g_{fs} Min (mS)	I_G Typ (pA)	$ V_{GS1} - V_{GS2} $ Max (mV)
U440	-1 to -6	-25	4.5	-1	10
U441	-1 to -6	-25	4.5	-1	20

FEATURES

- Two-Chip Design
- High Slew Rate
- Low Offset/Drift Voltage
- Low Gate Leakage: 1 pA
- Low Noise
- High CMRR: 85 dB.

BENEFITS

- Minimum Parasitics Ensuring Maximum High-Frequency Performance
- Improved Op Amp Speed, Settling Time Accuracy
- Minimum Input Error/Trimming Requirement
- Insignificant Signal Loss/Error Voltage
- High System Sensitivity
- Minimum Error with Large Input Signal

APPLICATIONS

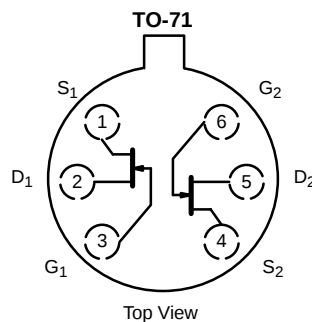
- Wideband Differential Amps
- High-Speed, Temp-Compensated, Single-Ended Input Amps
- High-Speed Comparators
- Impedance Converters

DESCRIPTION

The U440/441 are matched pairs of JFETs mounted in a single TO-71 package. This two-chip design reduces parasitics and gives better performance at very high frequencies while ensuring extremely tight matching. These devices are an excellent choice for use as wideband differential amplifiers in demanding test and measurement applications.

The hermetically-sealed TO-71 package is available with full military screening per MIL-S-19500 (see Military Information).

For similar products in SO-8 packaging see the SST440/SST441 data sheet. For low-noise options, see the SST/U401 series data sheet. For low-leakage alternatives, see the U421/423 data sheet.



ABSOLUTE MAXIMUM RATINGS

Gate-Drain, Gate-Source Voltage -25 V
 Gate-Gate Voltage ± 50 V
 Gate Current 50 mA
 Lead Temperature (t_{16} from case for 10 sec.) 300°C
 Storage Temperature -65 to 200°C

Operating Junction Temperature -55 to 150°C
 Power Dissipation : Per Side^a 250 mW
 Total^b 500 mW

Notes

- a. Derate 2 mW/°C above 25°C
 b. Derate 4 mW/°C above 25°C

SPECIFICATIONS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Conditions	Typ ^a	Limits				Unit
				U440		U441		
				Min	Max	Min	Max	
Static								
Gate-Source Breakdown Voltage	V _{(BR)GSS}	I _G = −1 μA, V _{DS} = 0 V	−35	−25		−25		V
Gate-Source Cutoff Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 nA	−3.5	−1	−6	−1	−6	
Saturation Drain Current ^b	I _{DSS}	V _{DS} = 10 V, V _{GS} = 0 V	15	6	30	6	30	mA
Gate Reverse Current	I _{GSS}	V _{GS} = −15 V, V _{DS} = 0 V	−1		−500		−500	pA
		T _A = 125° C	−2					nA
Gate Operating Current	I _G	V _{DG} = 10 V, I _D = 5 mA	−1		−500		−500	pA
		T _A = 125° C	−0.3					nA
Gate-Source Forward Voltage	V _{GS(F)}	I _G = 1 mA , V _{DS} = 0 V	0.7					V
Dynamic								
Common-Source Forward Transconductance	g _{fs}	V _{DS} = 10 V, I _D = 5 mA f = 1 kHz	6	4.5	9	4.5	9	mS
Common-Source Output Conductance	g _{os}		70		200		200	μS
Common-Source Input Capacitance	C _{iss}	V _{DS} = 10 V, I _D = 5 mA f = 1 MHz	3					pF
Common-Source Reverse Transfer Capacitance	C _{rss}		1					
Equivalent Input Noise Voltage	e _n	V _{DS} = 10 V, I _D = 5 mA f = 10 kHz	4					nV/ √Hz
Matching								
Differential Gate-Source Voltage	V _{GS1} − V _{GS2}	V _{DG} = 10 V, I _D = 5 mA	6		10		20	mV
Gate-Source Voltage Differential Change with Temperature	$\frac{\Delta V_{GS1} - V_{GS2} }{\Delta T}$	V _{DG} = 10 V, I _D = 5 mA T _A = −55 to 125° C	20					μV/° C
Saturation Drain Current Ratio ^c	$\frac{I_{DSS1}}{I_{DSS2}}$	V _{DS} = 10 V, V _{GS} = 0 V	0.97					
Transconductance Ratio ^c	$\frac{g_{fs1}}{g_{fs2}}$	V _{DS} = 10 V, I _D = 5 mA f = 1 kHz	0.97					
Common Mode Rejection Ratio	CMRR	V _{DG} = 5 to 10 V, I _D = 5 mA	85					dB

Notes

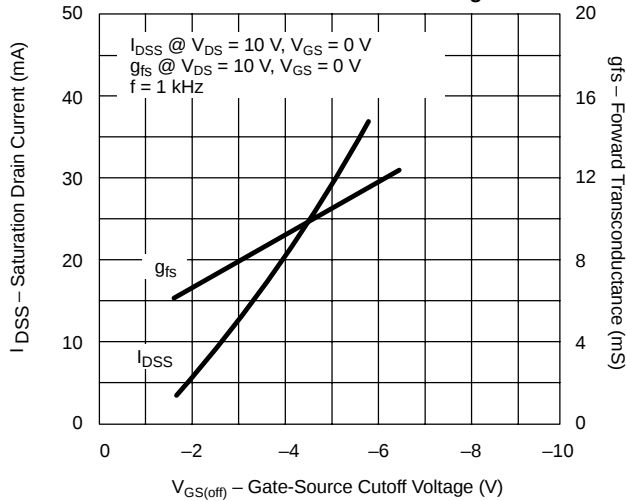
- a. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
b. Pulse test: $PW \leq 300\ \mu\text{s}$ duty cycle $\leq 3\%$.
c. Assumes smaller value in the numerator.

NZFD

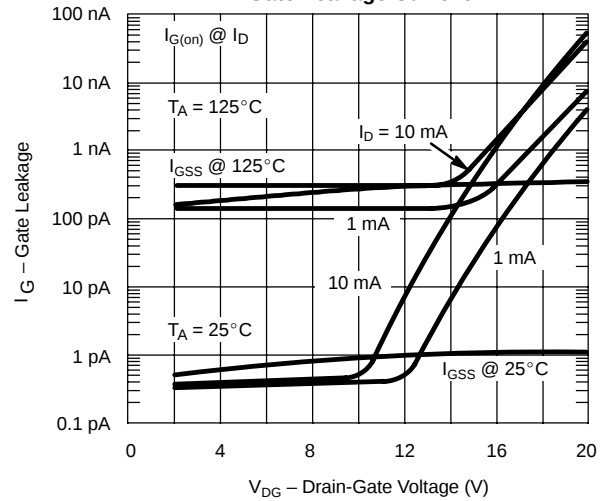


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

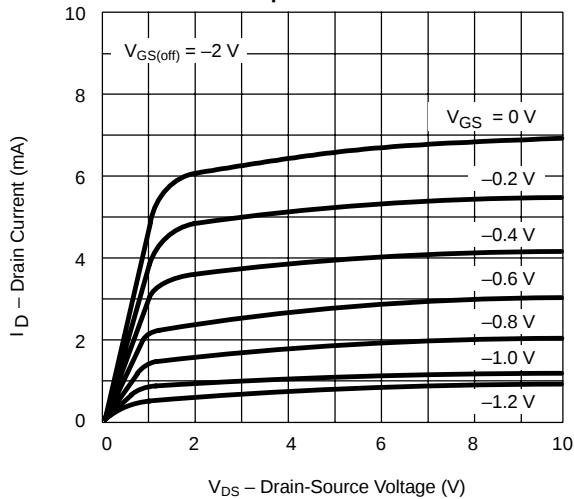
**Drain Current and Transconductance
vs. Gate-Source Cutoff Voltage**



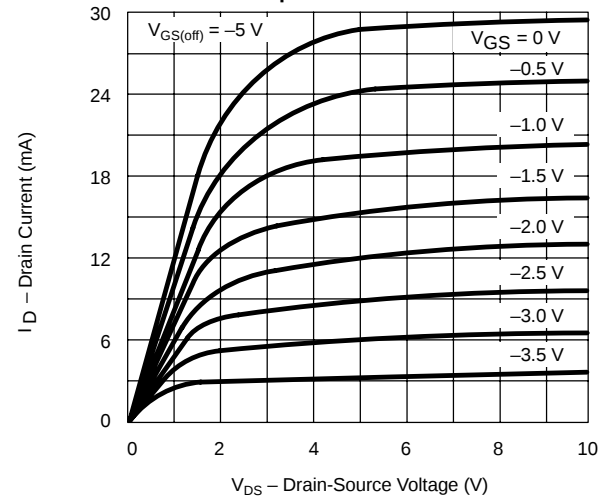
Gate Leakage Current



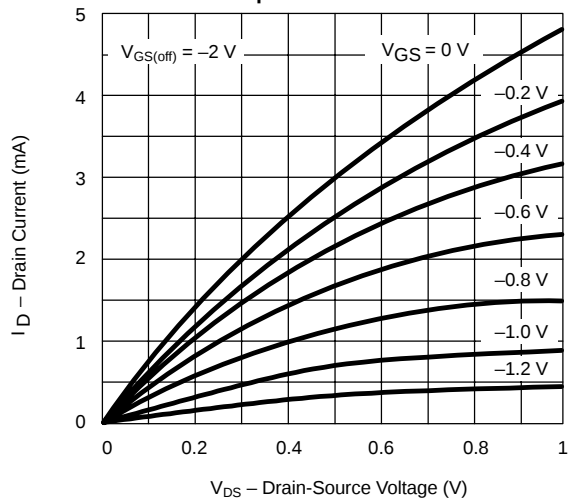
Output Characteristics



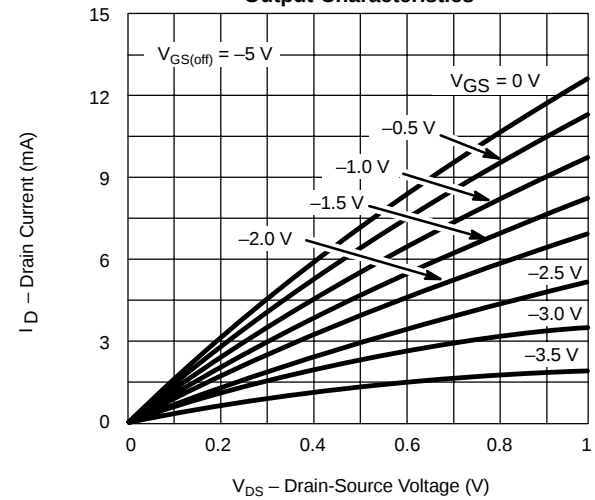
Output Characteristics

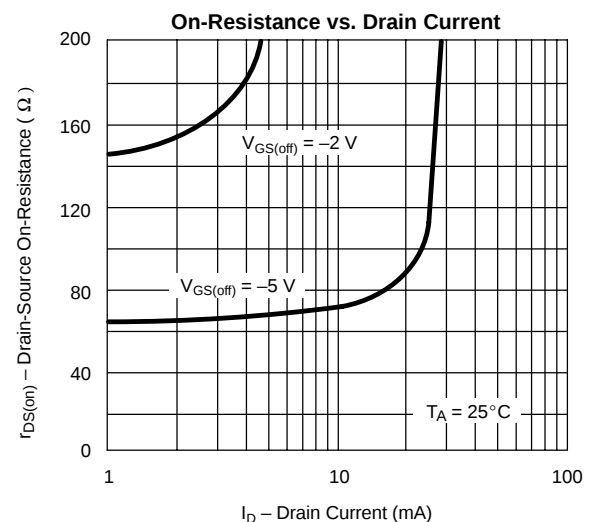
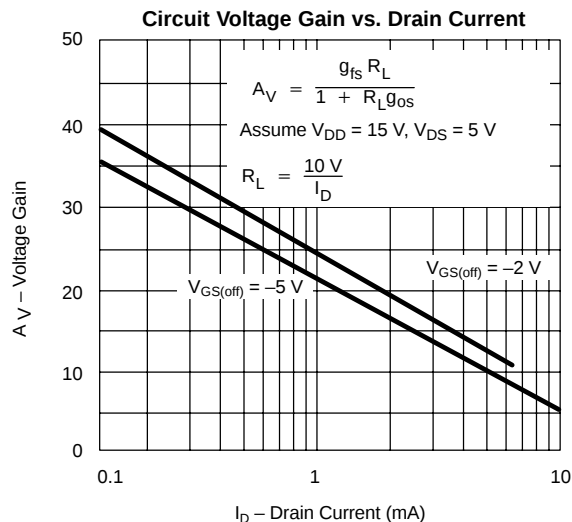
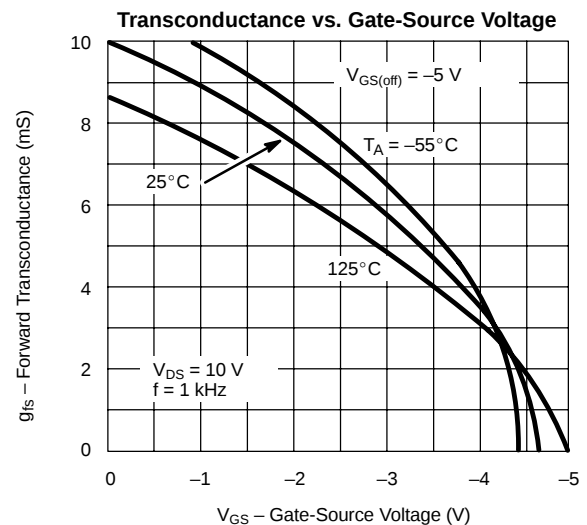
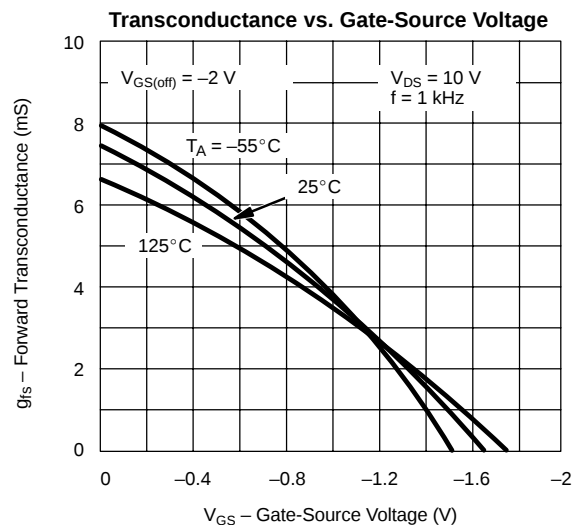
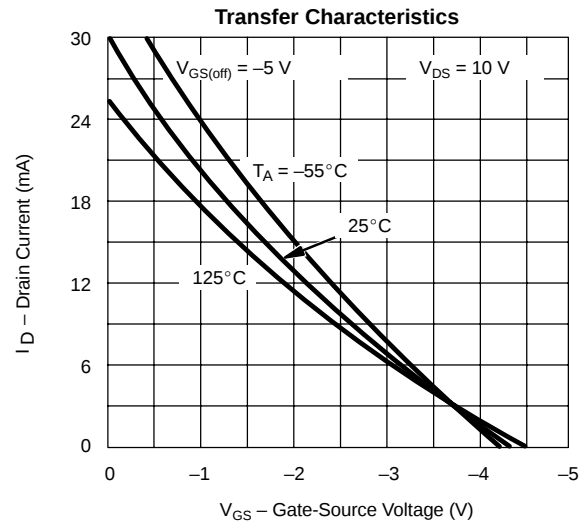
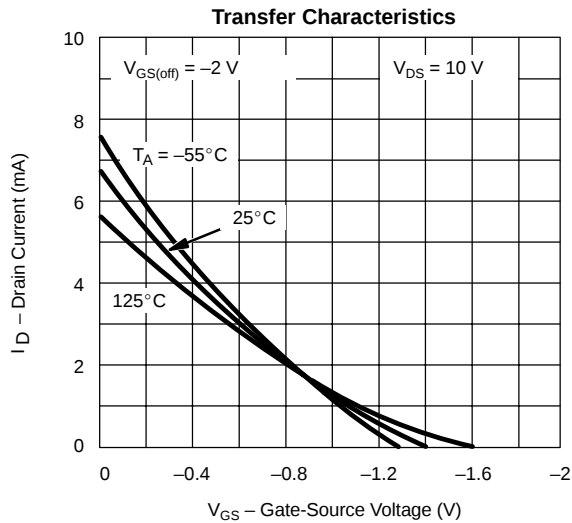


Output Characteristics



Output Characteristics

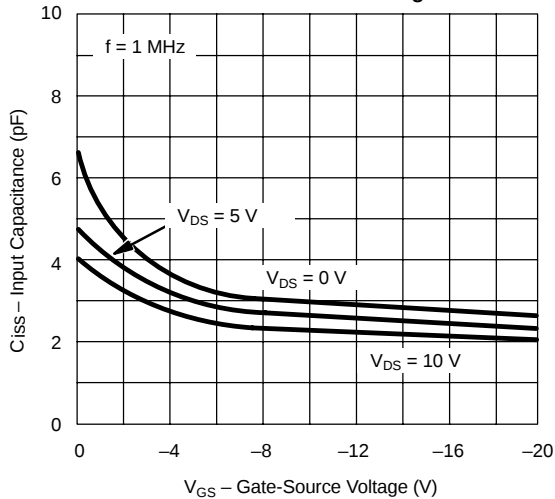


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)


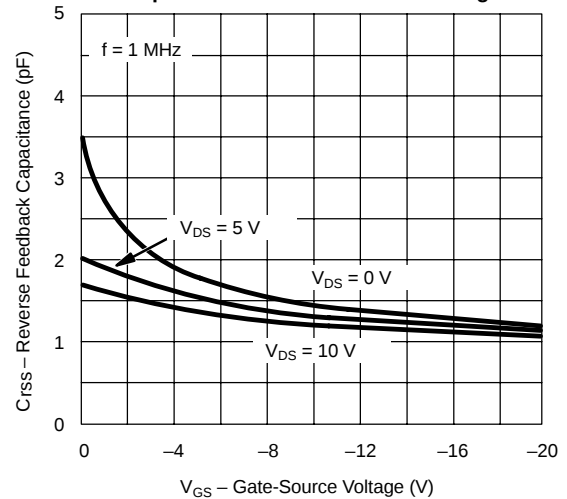


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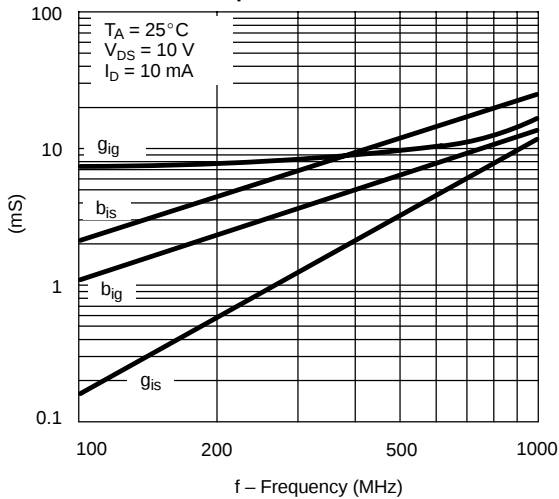
Common-Source Input Capacitance
vs. Gate-Source Voltage



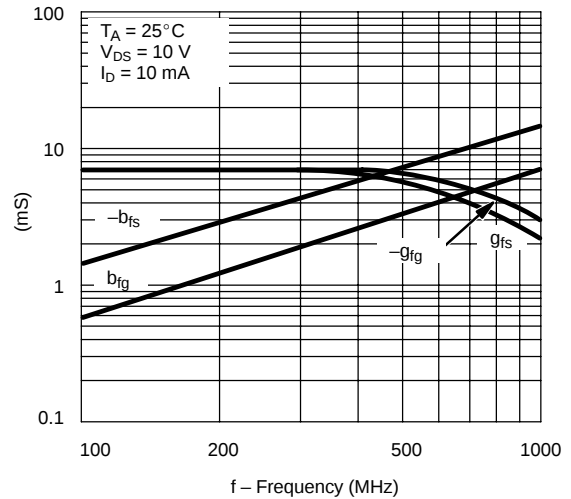
Common-Source Reverse Feedback
Capacitance vs. Gate-Source Voltage



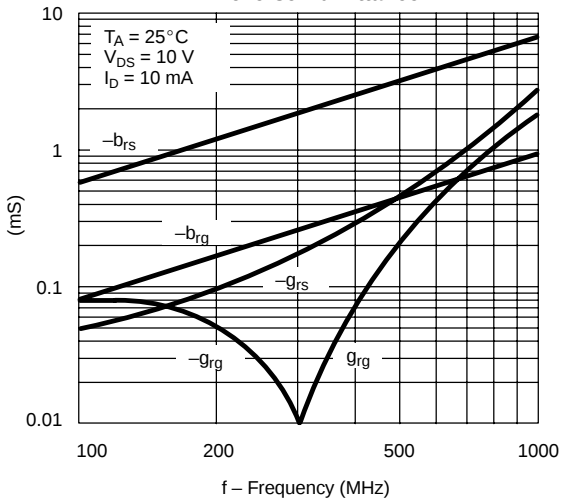
Input Admittance



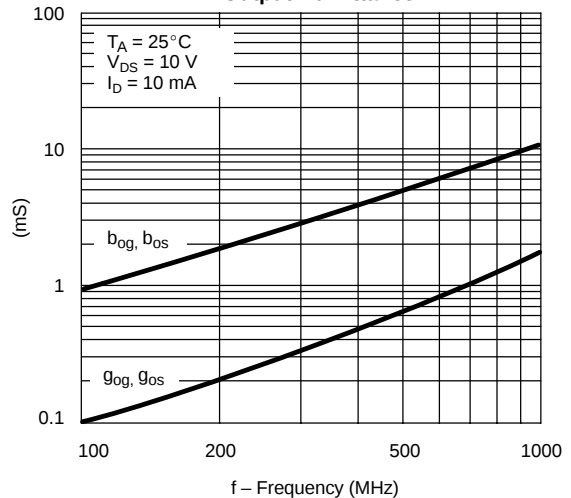
Forward Admittance

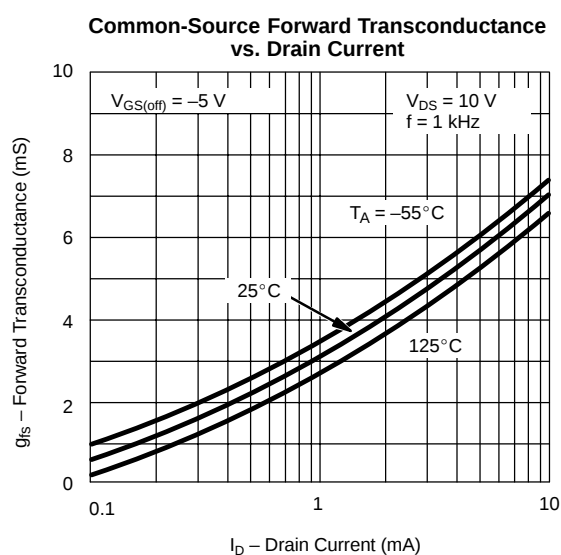
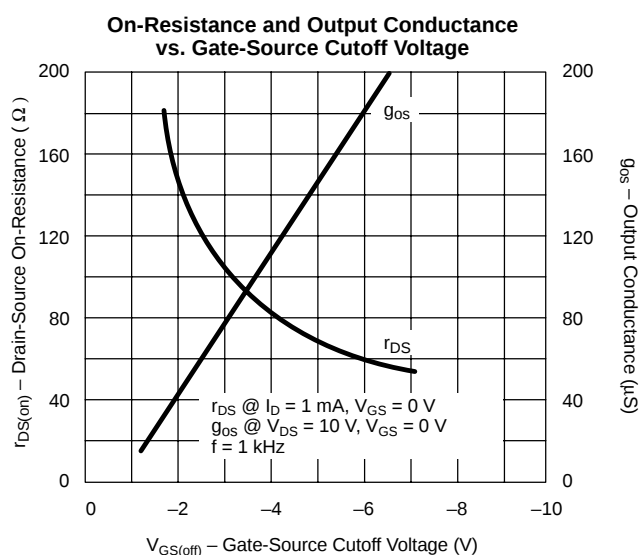
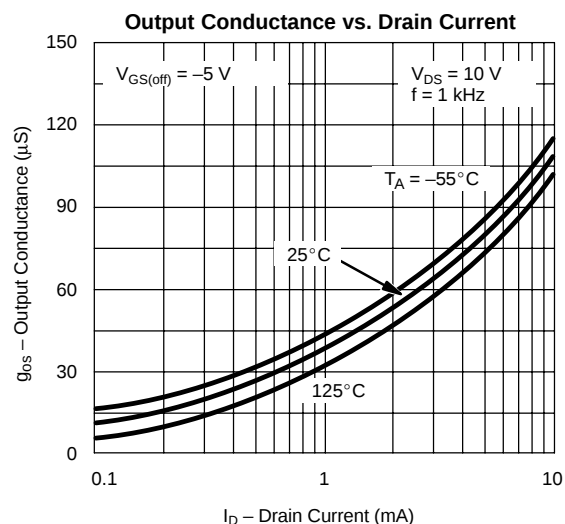
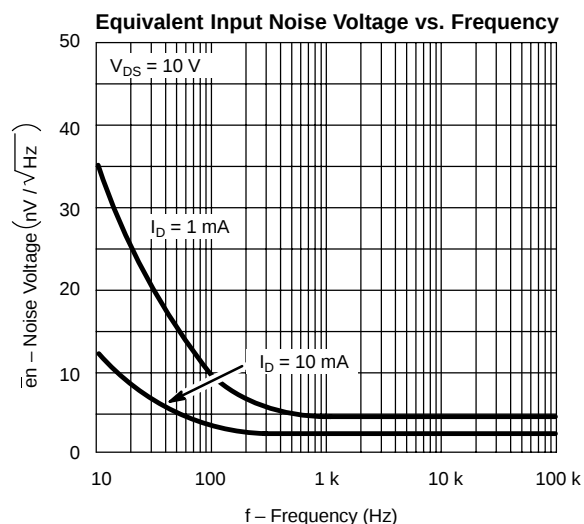


Reverse Admittance



Output Admittance



TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)




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